

METHOD FOR FABRICATING A GOLD CONTACT ON A
MICROSWITCH

ABSTRACT OF THE DISCLOSURE

Described is a process to pattern adhesion and top contact layers in such a way that at least some portion of the top contact layers overlaps the adhesion layer, while another portion of the top contact layer overlaps with the bottom contacts, but does not overlap with the adhesion layer. The overlap between the top contact layer and the adhesion layer helps to hold the top contact layer onto the sacrificial layer. Because there is no overlap between the adhesion layer and the bottom contact, the removal of adhesion layer is no longer necessary, leading to better contacts and simplifying the fabrication process.